

06-07-2005



Docket No. JCLA13058

103015731

Form 1595
1-31-92

RECORDATION FORM COVER SHEET

U.S. Department of Commerce
Patent and Trademark Office

PATENTS ONLY

To the Honorable Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.

50-18-50

1. Name of conveying party(ies):
I-Tseng Lee

2. Name/address of receiving Party(ies):
VIA Technologies, Inc.

8F, No. 535, Chung-Cheng Rd.,
Hsin-Tien City, Taipei Hsien,
Taiwan, R.O.C.

3. Nature of conveyance: Assignment
 Merger Security Agreement Other
 Change of Name Reassignment

4. Date(s) of execution: February 25, 2005.

Add'l names of receiving parties
Attached? Yes No

5. Application number(s) or patent number(s):
If this documents is being filed together with a new application, the execution date of the application is February 25, 2005.

A. Patent Application No. (s)

B. Patent No. (s)

Additional numbers attached ? Yes No

6. Name and address of party to whom Correspondence concerning document should be mailed:

J.C. Patents, Inc.
4 Venture, Suite 250
Irvine, CA 92618
(949) 660-0761

7. Total No. of applications and patents involved:
ONE(1)

8. Total fee (37 CFR §3.41): \$40.00
 Enclosed
 Charge to Acct. No. _____

9. Total number of pages, including Cover sheet, attachments and document 3.

DO NOT USE THIS SPACE

10. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Jiawei Huang
Name of Person Signing

[Signature]
Signature

5/31/2005
Date

Registration No. 43,330

06/06/2005 BYRME 0000188 11140708
01 FC:8021 40.00 DP

113256 U.S. PTO
11/140708



ASSIGNMENT

WHEREAS,

1. I-Tseng Lee

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **CIRCUIT BOARD AND PROCESSING METHOD THEREOF**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, VIA Technologies, Inc.
of 8F, No. 535, Chung-Cheng Rd., Hsin-Tien City, Taipei Hsien, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: I-Tseng Lee Date: FEB.25,2005

Sole or First Joint Inventor: **I-Tseng Lee**